APPROVAL

PART NO.	DESCRITION	REMARKS
HT2403L	LCD MODULE (240 × RGB × 320 Dots)	* ROHS compliant

CUSTOMER APPLICATION	P/N					
APPROVED BY						
DATE						
PLEASE KINDLY FIND HEREIN AND RETURN			-	TIONS INSERTED JR SIGNATURE OF APPROVAL.		
PERPARED BY		CHECKED BY		CONFIRMED BY		
HYES Optoelectronics, Inc. 2000 Wyatt Drive Suite 6 Santa Clara, CA 95054 USA						
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REVISION HISTORY

Date	Rev. No.	Page	Summa	ıry
Aug. 26, 20	- 800	ALL	- 1'st Issue	
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1. Basic Specfications

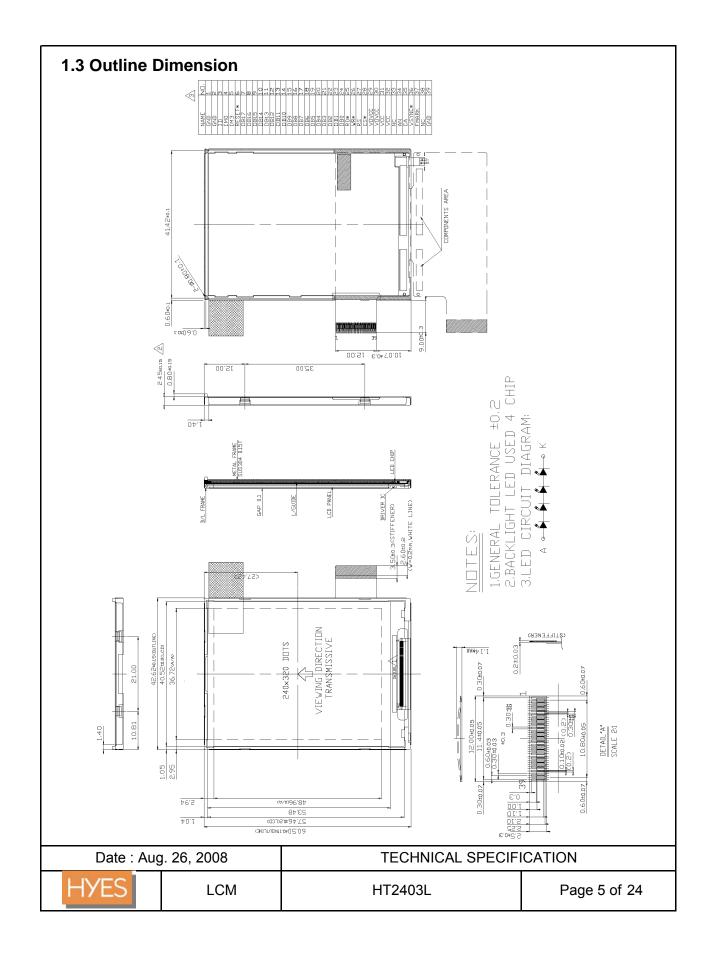
1.1 Display Specifications

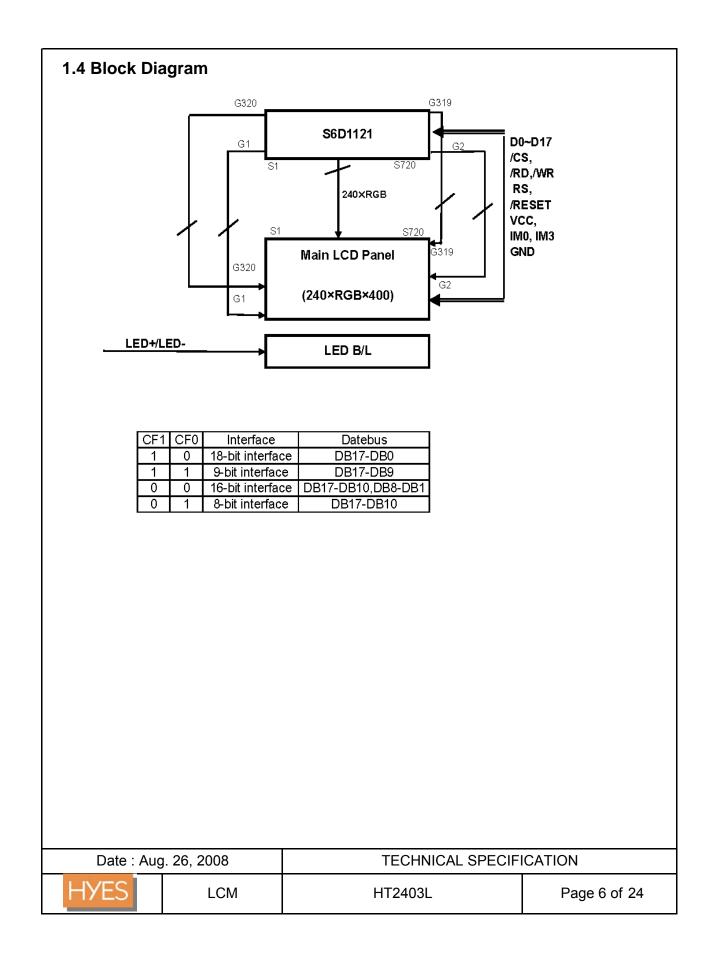
Item	Description	Note
Resolution	240 × RGB × 320	
Display mode	TFT, Normally White, Transmissive	
Viewing direction	6 O'clock	
Driving method	720Ch-Source, 320Ch-Gate	
Backlighting	LED, White (4 chips in Serial)	
Diver IC	S6D1121, COG	
Others	80-Series, 18/16/9/8-Bit Parallel	

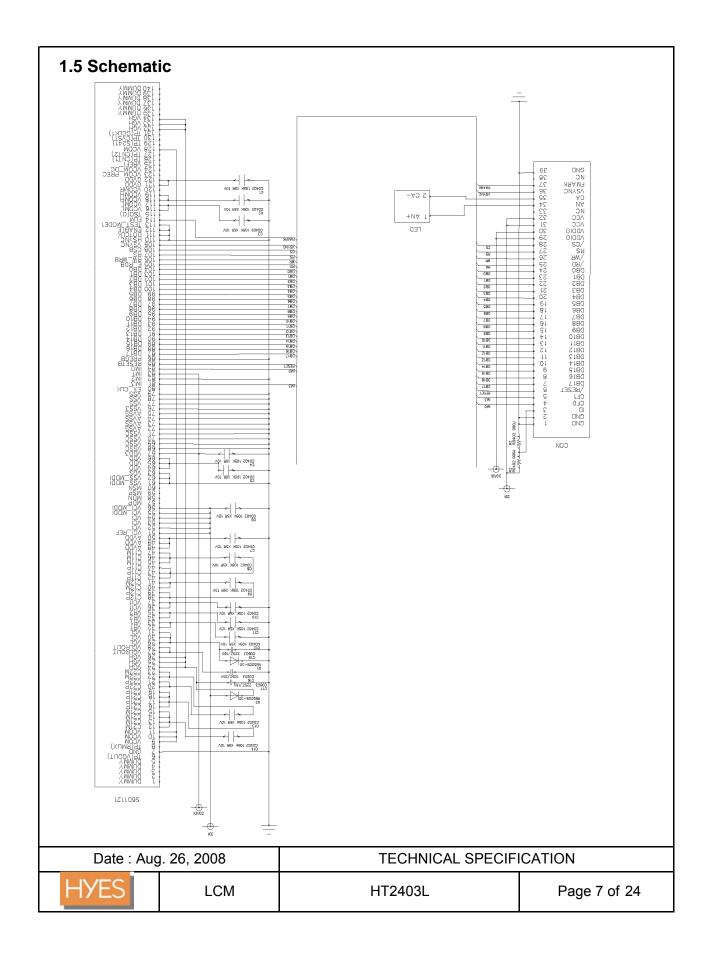
1.2 Mechanical Specifications

Item	Specification	Unit
Module Size (W × H × T)	42.62 × 60.5 × 2.45	mm
Viewing Area (W × H)	-	mm
Active Area (W × H)	36.72 × 48.96	mm
Dot Size (W × H)	-	mm
Dot Pitch (W × H)	0.051 × 0.153	mm
Weight	About 10	g

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2. Electrical Characteristics

2.1 Absolute Maximum Ratings

Item		Symbol	Value		Unit	Condition	Remark	
nem		Symbol	Min.	Тур.	Max	Onit	Condition	Remark
Supply	Logic	VDDIO	-0.3	-	5.0	V	Ta =25℃	
Voltage Range	Power Supply	VCC	-0.3	-	5.0	V	Ta =25 ℃	
	LCD	VGH-VGL	-0.3	-	35.0	V	Ta =26 ℃	
Input Volta	age	V _{IN}	-0.3	-	VCC+0.5	V	Ta =25℃	

2-2 Environmental Conditions

Item	Symbol	Min.		Max.	Unit
Operating temperature	Topr	-20		70	Ĉ
Storage temperature	Tstg	-30		80	Ĵ
Humidity (Ambient temperature=Ta)	Ta ≤ 60 °C			90% RH max	

2-3 DC Characteristics

Items		Sysbol		Spec. Value	Unit	Condition	
items		Sysbol	MiN. Typ. Max.			Onit	Condition
	Ligic	VDDIO	1.65	1.8	3.3	V	
Operating Voltage	Power Supply	VCC	1.65	2.8	2.88	V	
Operating Voltage	GATE	VGH	7.5	-	18	V	Note1)
	GATE	VGL	-11	-	-5.5	V	Note I)
Supply current		ICC	-	9.5	14.3	mA	Note2)
Supply cul	rent						
Input voltage	High level	V _{IH}	$0.8 \times V_{CC}$	-	V _{cc}	V	-
input voltage	Low level	V _{IL}	0	-	0.2 × V _C	c V	-
Note1) The value car	n be adjusted b	y software to optimiz	ze display quali	ty.			
Note2) Display black							
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3. Optical Characteristics

Transmissive mode

(Ta = 25℃)

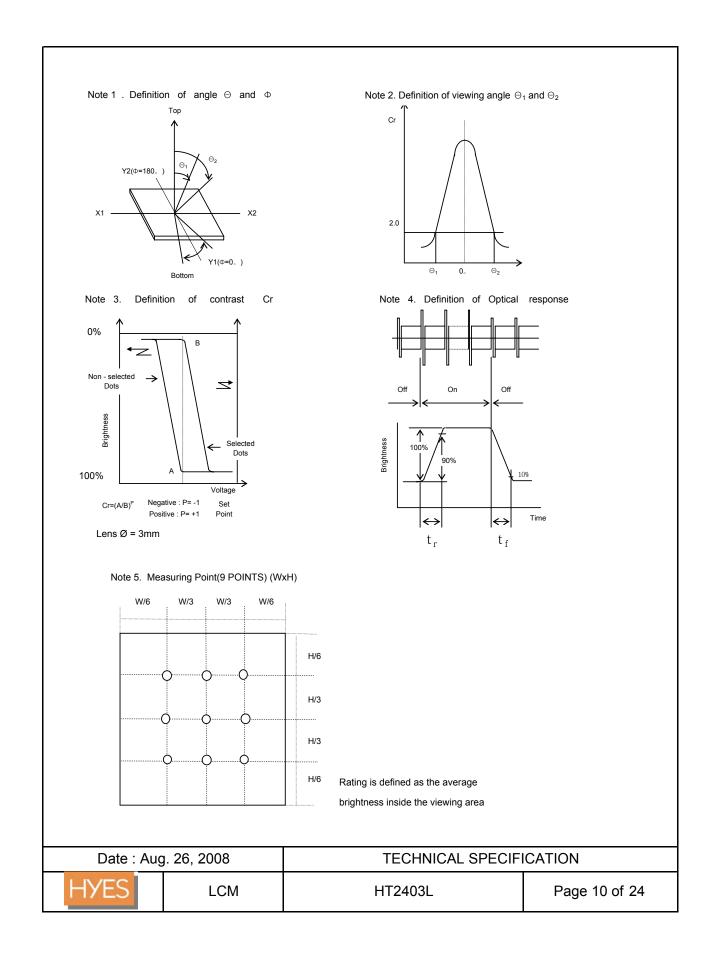
lte	m	Symbol		Min.	Тур.	Max.	Unit	Condition	Note
Viewin	N// ·		Ø=0 (Y1-Y2)		60	-	Dog	0	
Viewin	ig	θ2-θ1	Ø=90 (X1-X2)	80	90	-	Deg	Cr > 10	
Contra	st ratio	Cr		200	380	-	-	$ \theta = 0 $ $ \phi = 0 $	
Respon	se Time		Tr + Tf	-	25	40	ms	$ \theta = 0 $ $ \emptyset = 0 $	
CIE	R		(x,y)	0.58, 0.30	0.62, 0.34	0.68, 0.38			
Coordi	G		(x,y)	0.28, 0.55	0.32, 0.59	0.38, 0.63		θ = 0	
- nate	В		(x,y)	0.01, 0.04	0.14, 0.08	0.18, 0.12		Ø = 0	
	W		(x,y)	0.24, 0.26	0.28, 0.30	0.32, 0.34			
Brigh	tness		L	230	290	-	cd/m2	18mA/LED	
Unifo	ormity			70	-	-			

* $\emptyset = 0^\circ$, $\emptyset = 90^\circ$ means viewing direction.

* B/L is turned on.

* Remark : as for contrast ratio, it is measured in panel only.

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4. Interface Pins

No.	symbol		Description	
1	GND	Ground		
2	GND	Ground		
3	ID	ID bit se	tting of device ID code	
4	CF0		erface Mode Selection(IM0)	
5	CF1		erface Mode Selection(IM3)	
6	RESET	RESET S	signal(low active)	
7	DB17		s (Instruction & Display Data)	
8	DB16	Data Bu	s (Instruction & Display Data)	
9	DB15		s (Instruction & Display Data)	
10	DB14		s (Instruction & Display Data)	
11	DB13	Data Bu	s (Instruction & Display Data)	
12	DB12		s (Instruction & Display Data)	
13	DB11	Data Bu	s (Instruction & Display Data)	
14	DB10		s (Instruction & Display Data)	
15	DB9	Data Bu	s (Instruction & Display Data)	
16	DB8	Data Bu	s (Instruction & Display Data)	
17	DB7	Data Bu	s (Instruction & Display Data)	
18	DB6	Data Bu	s (Instruction & Display Data)	
19	DB5	Data Bu	s (Instruction & Display Data)	
20	DB4	Data Bu	s (Instruction & Display Data)	
21	DB3	Data Bu	s (Instruction & Display Data)	
22	DB2	Data Bu	s (Instruction & Display Data)	
23	DB1	Data Bu	s (Instruction & Display Data)	
24	DB0	Data Bu	s (Instruction & Display Data)	
25	RD	Read Si	gnal	
26	WR	Write Si	gnal	
27	RS	Data/co	mmand identif icasion	
28	CS	Chip Se	lect	
29	VDDIO	Power S	Supply for Interface (1.8V)	
30	VDDIO	Power S	Supply for Interface (1.8V)	
31	VCC		Supply for Analog and Logic (2.8V)	
32	VCC		Supply for Analog and Logic (2.8V)	
33	NC	No conn		
34	AN		Supply for LED	
35	CA	GND for		
36	VSYNC		synchronous signal	
37	FMARK		nead pulse signal	
38	NC	No conn	nection	
39	GND	Ground		
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5. Backlight Specfication (LED Unit)

ltom	Symbol		Spec. Value	е	Unit	Condition
ltem	Symbol	Min.	Тур.	Max.	Unit	Condition
Real Current	I _{LED}	-	18	20	mA	note 1.
Power dissipation	PD	-	-	160	mW	note 2.
Operation temp.	Topr		- 20 ~ 70		Ĵ	-
Storage temp.	Tstr		- 30 ~ 80		Ĵ	-

Note 1. B/L: 4EA LED in Serial, the typical current is 18mA (full brightness).

Note2. Total power consumpation (max) depends on LED current/ LED driver efficiency, etc.

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6. Recommended Software Setting Values (Initial code)

LDI :S6D1121

0011	
	1D04
0012	0033
0013	CC00
0015	382E
0014	002A
0013	CC04(DELAY 10ms)
0013	CC06(DELAY 50ms)
0013	CC4F(DELAY 10ms)
0013	674F
0011	1D02
0030	0100
0031	220E
0032	211F
0033	2423
0034	2628
0035	3127
0036	211E
0037	1723
	0F15
0039	0A0A
003A	1315
003B	3619
	0102
003D	0000
0016	0006
	0127
0002	0013
	0003
0008	0208
000A	0507
000B	0000
000C	0003
0041	0000
0050	0000
	0005
	0008
	0000
	0000
0079	0000
007A	0000(DELAY 50ms)
	0015 0014 0013 0013 0013 0013 0013 0013 0031 0030 0031 0032 0033 0034 0035 0036 0035 0036 0037 0038 0039 0038 0039 0038 0039 0038 0039 0038 0039 0030 0030

	REG NO	VALUE
	0007	0051(DELAY 50)ms
D	0007	0053(DELAY 20)ms
N S	0020	0000
P	0021	0000
	0022	

Standby on sequence

Display off s	equence
0007	0052(DELAY 40ms)
0007	0050
0007	0010
Power off se	quence
0012	0000
0013	CC46(DELAY 50ms)
0013	CC44(DELAY 50ms)
0013	CC40
set standby	mode
0010	0001

Standby off sequence

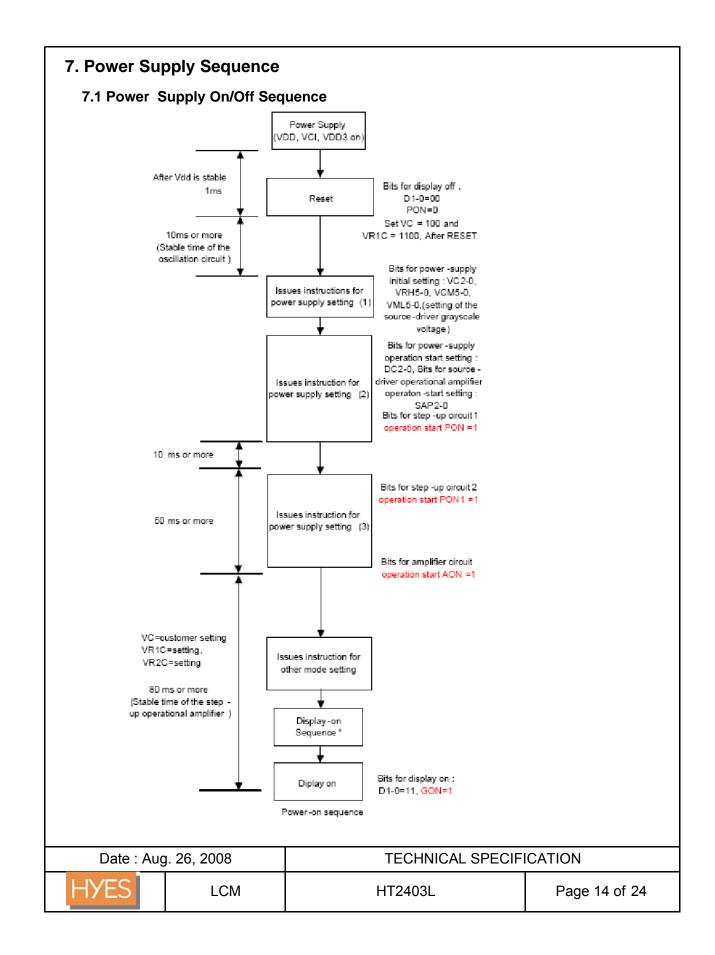
0004	2501(DELAY 20ms)				
0010 0000(DELAY 20ms)					
Call power on sequence					
Call display	on sequence				

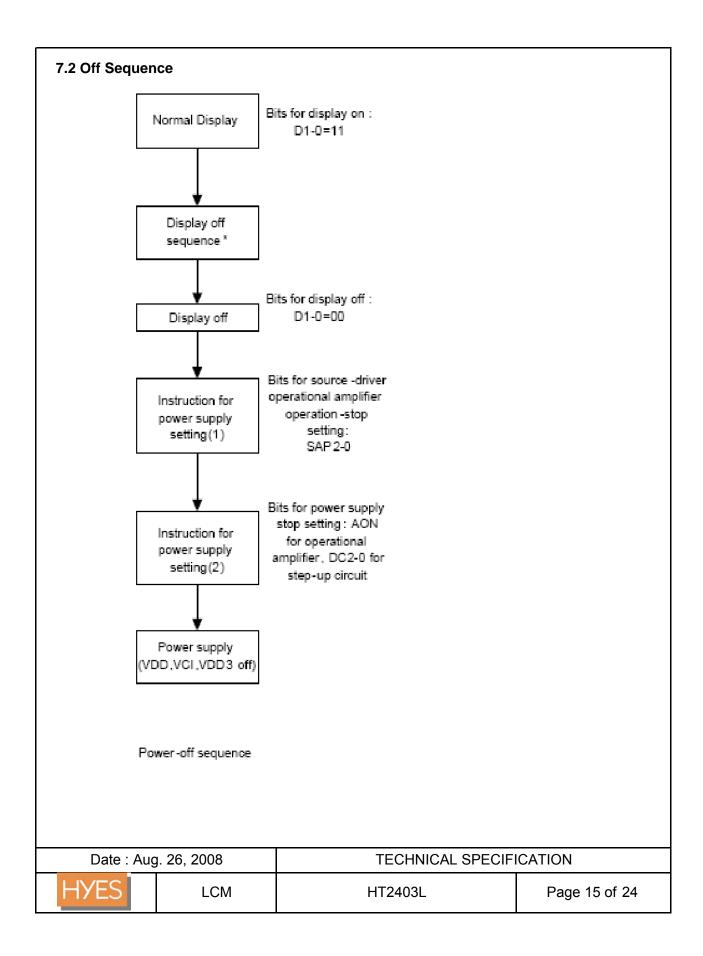
Partial display sequence

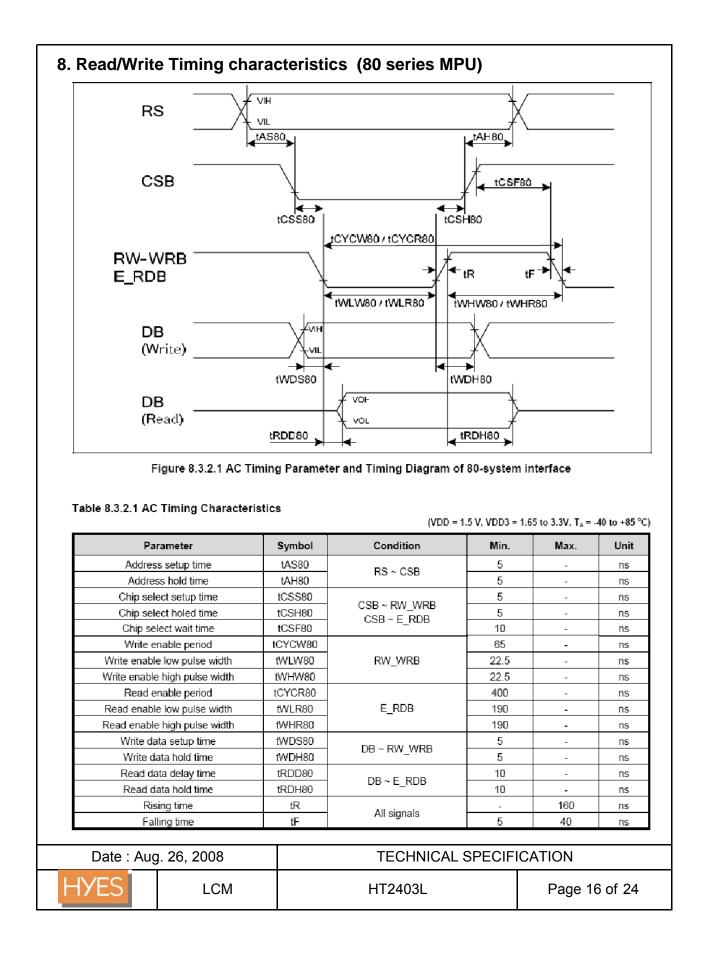
0007	0053
0042	the end of 1st screen
0043	the start of 1st screen
0044	the end of 2nd screen
0045	the start of 2nd screen
DELAY 50ms	5
0007	4153
Return to fu	ll display
0042	013F
0043	0000
0044	013F
0045	0000
END	

ions strictly. If customer would like to change S and get re-check from HYES, result because of the change.

	inci wiii be responsibi	c for any unexpected result because of the t	shange.
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			— tRES —			
RES						
	Figure 8.6.1 AC	Timing Paramete	r and Timing D	liagram of R	ESET	
Table 8.6.1 A	C Characteristics of RESE	ET				
	Characteristic		(VE Symbol	D = 1.5 V, VDE Min.	03 = 1.65 to 3.3V, 1 Max.	Γ _A = -40 to +85 °C) Unit
	Reset low pulse width		tRES	15	-	us
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9. LCD Module Out-Going Quality Level

(1.0) Purpose

The LCD specification provides outgoing provision and its expected quality level based on our outgoing inspection of LCD.

(2.0) Applicable Scope

The LCD specification is applicable to the arrangement in regard to outgoing Inspection and quality assurance after it.

(3.0) Quality Specification

(3.1) Quality Level

The quality level of HYES are based on GB/T2828.1, Apply Level II,

normal inspection by single sampling.

Rank	Item	AQL	Note
Major(MA)	Segment Short, Missing	0.65	
	Solder Bridging, Cold Solder		
	Outside Dimension		
Minor (MI)	Black Spots, White Spots, Foreign Substance,	1.0	
	Pinhole, Segment Deformation, Scratchs(Glass & Pol.)		
	Air Bubbles between Glass & Polarizer,		
	Color Variation, Solder Ball, Misalignment		

Note) AQL- Acceptable Quality Level

(3.2) Appearance Standards

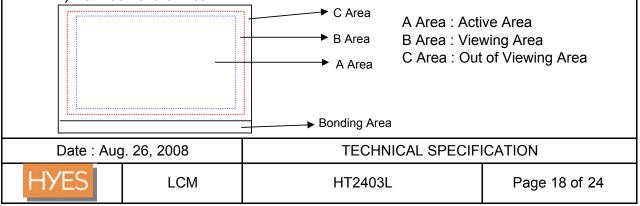
1) Inspection Conditions

The LCD shall be inspected under 20W white fluorescent lamp light.

The distance between the eyes and the sample shall be 30cm.

All directions for inspecting the sample should be within 30° to perpendicular line.





١o	Item			Criteri	a		Rank	Remark
1	Segment Short Segment Missing	Not allowe	d				MA	
2	Solder Bridging		-	n component			MA	
-				it, is not allo				
3	Outside Dimension		-	ion must be	within		MA	
4	G-11 G-11-	permitable Cold solde						
4	Cold Solder	_		wed.			MA	
5	Black(White) Spots, Foreign	1) Round 7	l ype				MI	¥
	Substances	A	rea	Accepta	ıble Q'ty	Remark		
		Dime	nsion**	A Area	B Area			
		≦	0.1	Ign	lore			() ↓×
		≤	0.2	2	Ignore		1	
		≦	0.3	1	Ignore		1	** : Mear
		0.3 <	<u> </u>	0	Ignore			Diameter
		2) Liner Ty	/De					(X + Y)/2
			ension	Accents	ible Q'ty	Remark		
		Length	Width	A Area	B Area	Roman		
			≤ 0.025		lore			
		≤ 2.5	≤ 0.05	3	Ignore			
		≤ 1.5	≤ 0.075	2	Ignore			
		- 1.5	0.075 <		ound type			
		At (1) & (exceed 5	(2) total def	fect q'ty is n				
6	OC Spot							1
~							MI	
v	1	A	rea	Accepta	ible Q'ty	Remark	MI	
v	1		rea nsion**	Accepta A Area	ible Q'ty B Area	Remark	MI	
v		Dime		A Area		Remark	MI	
v		Dime	nsion** 0.2	A Area	B Area	Remark	MI	
v		Dime	nsion** 0.2 0.8	A Area Igr	B Area	Remark	MI	
		Dime:	nsion** 0.2 0.8	A Area Igr 3	B Area tore Ignore	Remark		
7	Air Bubles	Dime S S S S S S S S S S S S S	nsion*** 0.2 0.8 1.0	A Area Igr 3 1	B Area nore Ignore Ignore		MI	
	Air Bubles Between Glass &		nsion*** 0.2 0.8 1.0 rea	A Area Igr 3 1	B Area tore Ignore	Remark		
	Air Bubles Between Glass & Polarizer	Dime:	nsion*** 0.2 0.8 1.0 rea nsion***	A Area Igr 3 1 Accepta A Area	B Area tore Ignore Ignore ble Q'ty B Area			
	Air Bubles Between Glass &	Dime Second Second Sec	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15	A Area Igr 3 1 Accepta A Area Igr	B Area lore Ignore Ignore ble Q'ty B Area			
	Air Bubles Between Glass & Polarizer	Dime Second And And And And And And And And And A	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15 0.3	A Area Igr 3 1 Accepta A Area Igr 3	B Area tore Ignore Ignore ble Q'ty B Area tore Ignore			
	Air Bubles Between Glass & Polarizer	Dime Second And And And And And And And And And A	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15 0.3 0.5	A Area Igr 3 1 Accepta A Area Igr	B Area tore Ignore Ignore ble Q'ty B Area tore Ignore Ignore			
	Air Bubles Between Glass & Polarizer	Dime Second Control C	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15 0.3 0.5	A Area Igr 3 1 Accepta A Area Igr 3 2	B Area Ignore Ignore Ignore able Q'ty B Area tore Ignore Ignore Ignore			
	Air Bubles Between Glass & Polarizer	Dime Second Control C	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15 0.3 0.5 0.7	A Area Igr 3 1 Accepta A Area Igr 3 2 1	B Area tore Ignore Ignore ble Q'ty B Area tore Ignore Ignore			
	Air Bubles Between Glass & Polarizer	Dime Second Control C	nsion*** 0.2 0.8 1.0 rea nsion*** 0.15 0.3 0.5 0.7	A Area Igr 3 1 Accepta A Area Igr 3 2 1 5	B Area lore Ignore Ignore bble Q'ty B Area lore Ignore Ignore Ignore Ignore		MI	

٩V	Item		Criteria	Rank	Remark
8	Pin hole (On Segment)	Total def	$(X+Y)/2 \le 0.2 \text{ mm}$ $\forall \text{Within 1 per one}$ segment (Less than 0.1 mm is not counted) Fects q'ty is must not exceed 5 pieces.	MI	
9	Segment Deformation	Each visib	$\begin{array}{c c} X \\ \hline X \\$	MI	(X + Y)/ ≤ 0.2m
10	Color Variation		ot area three colors, except LCD olor is acceptable.	MI	
11	Glass & Polarizer Scratch		0.5(2) condition	MI	
12	Solder Ball	than 0.18 2)Acceptal 3)Rejectab	ble if the size of void is less 3 mm ble if a solder ball is not movable le if the solder ball exceed $2.54 \times 2.54 \text{ mm}$ area.	MI	
13	Miss Alignment	1)Acceptal the lead W IC 2)Rejectab exceed 5	ble if it dose not exceed 50% of		
	Note : A limitation	sample is given top p			
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o Item		Criteria		Rank	Remark
4 Touch Panel	1) Round Type, For		MI		
	Area	Acceptable Q'ty	Remark		Y kanal
	Dimension**	A Area B Area	Keinark		
	≤ 0.1	Ignore			
	≤ 0.2	2 Ignore			
	≤ 0.3	1 Ignore			** : Mean
	0.3 <	0 Ignore			Diameter (X + Y)/2
	2) Liner Type & Scrat	2) Liner Type & Scratch			(X+1)/2
	Dimension	Acceptable Q'ty	Remark		
	Length Width	A Area B Area			
	- W≤0.02	5 Ignore			
	$L \leq 3.0$ $W \leq 0.0$	5 Ignore	4 _		
	3.0 <l≤5.0< td=""><td>2</td><td>Ignore</td><td></td><td></td></l≤5.0<>	2	Ignore		
	$ \leq 7 W \leq 0.1 $				
	i				
	It's NG.	n ring is more than 1/3area of n ring is less than 1/3 area of			
	It's NG.	u ung is more than 1/2 area of			
	The area of the Newton	ת יוחg is more than 1/2area of n ring is less than 1/2 area of			
	The area of the Newton It's NG. The area of the Newton				
Date : Au	The area of the Newton It's NG. The area of the Newton	n ring is less than 1/2 area of		CIFICAT	ION

(4.0) Reliability Condition

Item	Content
Room Temperature Operation	50,000 hrs

(4.1) Reliability Test - Module Middle Reliability

No.	Item	Condition	Test	Sample	Creteria	Note
			Time	Numbers	(Acc/Rej)	
1	High Temp	70 ± 2℃	120 hrs	3	0/1	
	Operation					
2	Low Temp	-20 ± 2℃	120 hrs	3	0/1	
	Operation					
3	High Humidity	ර°C	120 hrs	3	0/1	
	Storage	90%rh				
4	Thermal	30mn stage -20℃	100 cycles	3	0/1	
	Shock	⇔70°C	/6days			

(4.2) Criteria

- a. No changes for indication and appearance.
- b. Leave the all samples under roon temperature 4 hours after reliability test ends.

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10. LCD Module Operation Instruction

Part I. How to use the LCD Module

- 1. Don't hit the LCD Panel in any way because the LCD is made of glass.
- 2. Don't clean the surface of LCD with hard things. Please clean LCD with Air-gun or very soft cloth when necessary. The protective film on the POL can be removed just before assembly, otherwise,dust, spit or other foreign matter may attached on the LCD under the protective film. After the protective film is removed, only air-gun can be used to remove any dust or foreign matter. Fingure or cloth MUST NOT be used in such cases.
- 3. No chemical liquid is allowed to clean the LCD, such as alcohol, acetone and IPA. All of these candamage the LCD. Water on the LCD must be cleaned as soon as possible, for it will cause POL color change or other defect.
- 4. Please move and assemble LCD very carefully during assembly, and don't push or twist it.
- 5. Don't damage the FPC of LCD module. It will cause permanent defect.
- 6. Don't disassemble LCD module. It will cause permanent defect.
- 7. Don't expose LCD module under sunshine, strong fluorescence or ultraviolet radiation.
- 8. Please make sure that operators wear static-protective bands effectively and working tables are effectively earthing during operation.
- 9. Please place LCD module on the tray provided by HYES while moving it, in order to avoid mechanical damage. Hold the module's side frames to avoide damage during moving.
- 10. Don't twist, disassemble, squeeze or hit the PCB. It will damage the circuit or component on PCB and cause functional defect.
- 11. Please use the connector according to the instruction provided by HYES.
- 12. Please place dual module with the sub-panel upward. Trays should be placed in contrary direction. An empty tray should be placed on the top.
- 13. Sealing operation on PCB must be very careful to avoid short or cut the original circuit on PCB.Otherwise, it will cause permenant damage to the LCD.
- 14. Don't add direct DC or high voltage to LCD panel. It will cause functional damage to the LCD or shorten the life of LCD product.
- 15. LCD may respond slowly or display abnormally in extrem temperature (lower than -20°C or higher than 50°C). But this doesn't mean LCD functional defect. LCD will display normally in regular temperature. Therefore, don't use LCD product in extrem temperature.

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- 16. Don't push the display area of LCD panel, it will cause abnormal display. This doesn't mean LCD functional defect, neither. LCD will display normally in regular temperature.
- 17. Electrical test of LCD product is made by using mobile phone provided by Customer. We can use special test equipment to do the test, also.
- 18. The black band on IC on LCD product is used to protect the IC from light. Please do NOT remove it.
- 19. Please take great care to use connector. Customer should be responsible for connector defect caused by operation on Customer side.

Part II Storage

- 1. Physical status of liquid crystal will change in extrem temperature, and it can not be resumed when the temperature returns to be normal. So LCD module should be stored in required temperature.
- 2. LCD module should be stored in required humidity. Low hymidity may add static, while high humidity may corrode the ITO circuit of LCD product. The suitable storage environment is: temperature:22±5℃, humidity: 55%±10%.
- 3. Don't expose LCD module under sunshine, strong fluorescence or ultraviolet radiation for a long time. It should be stored in dark area.
- 4. LCD should be stored in static-protective polythene bag. Don't expose it in the air for a long time.

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